

SGM6014 1.4MHz, 2A Synchronous Step-Down Converter

GENERAL DESCRIPTION

The SGM6014 is a high efficiency monolithic synchronous step-down regulator using 1.4MHz constant frequency, current mode architecture. The device is available in an adjustable version. It is ideal for portable equipment requiring very high current up to 2A from single-cell Li-Ion batteries while still achieving over 95% efficiency during peak load conditions. The SGM6014 can enter pulse frequency modulation (PFM) (low I_Q) mode with typically 55µA quiescent current for highest light load efficiency to maximize battery life.

The SGM6014 also can run at 100% duty cycle for low dropout operation, extending battery life in portable systems while light load operation provides very low output ripple for noise sensitive applications. It can supply up to 2A output load current from a 2.5V to 5.5V input voltage and the output voltage can be regulated as low as 1.2V. The high switching frequency (1.4MHz) minimizes the size of external components while keeping switching losses low. The internal slope compensation setting allows the device to operate with smaller inductor values to optimize size and provide efficient operation.

SGM6014 is available in both adjustable and 3.3V fixed output voltage versions; in the Green TDFN-3×3-10L package. It is rated over the -40°C to +85°C temperature range.

TYPICAL APPLICATION

FEATURES

- High Efficiency: Up to 95%
- 2.5V to 5.5V Input Voltage Range
- 1.4MHz Constant Frequency Operation
- 2A Output Current
- 3.3V Fixed and Adjustable Output Voltages
- 100% Duty Cycle for Lowest Dropout
- Less than 2µA Shutdown Current
- Low Quiescent Current: 55µA in PFM Mode
- Low R_{DS(ON)} Internal Switches: 0.135Ω
- Allows Use of Ceramic Capacitors
- Current Mode Control for Excellent Line and Load Transient Response
- Internal Soft-Start Protection
- Short Circuit and Thermal Protection
- -40°C to +85°C Operating Temperature Range
- Available in Green TDFN-3×3-10L Package

APPLICATIONS

PDA, Pocket PC and Smart Phones USB Powered Modems CPUs and DSPs PC Cards and Notebooks Cellular Phones Digital Cameras DSP Core Supplies Portable Instruments





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SEPTEMBER 2017 - REV. A. 3

PACKAGE/ORDERING INFORMATION

MODEL	V _{OUT} (V)	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM6014	Adjustable	TDFN-3×3-10L	-40°C to +85°C	SGM6014-ADJYTD10G/TR	SGM SHDD XXXXX	Tape and Reel, 3000
	3.3	TDFN-3×3-10L	-40°C to +85°C	SGM6014-3.3YTD10G/TR	SGM SIBD XXXXX	Tape and Reel, 3000

NOTE: XXXXX = Date Code and Vendor Code.

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Input Supply Voltage0.3V to 6V
EN Voltage0.3V to V_{IN} + 0.3V
FB/OUT, SW Voltages0.3V to V_{IN} + 0.3V
Power Dissipation, $P_D @ T_A = +25^{\circ}C$
TDFN-3×3-10L2.2W
Package Thermal Resistance
TDFN-3×3-10L, θ_{JA}
Junction Temperature+150°C
Storage Temperature Range65°C to +150°C
Lead Temperature (Soldering, 10s)+260°C
ESD Susceptibility
HBM
MM200V

RECOMMENDED OPERATING CONDITIONS

Input Voltage Range	2.5V to 5.5V
Operating Temperature Range	40°C to +85°C

OVERSTRESS CAUTION

Stresses beyond those listed may cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational section of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

ESD SENSITIVITY CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time.



PIN CONFIGURATION



PIN DESCRIPTION

PIN	NAME	FUNCTION
1	EN	Enable Pin. Pulling EN to ground forces the device into shutdown mode. Pulling EN to IN enables the device. EN should not be left floating and must be terminated.
2	IN	Supply Voltage Input. Must be closely decoupled to GND, with a $22\mu\text{F}$ or greater ceramic capacitor.
3	AIN	Analog Supply Input. Provides bias for internal circuitry.
4, 6	GND	Analog Ground.
F	FB	Feedback Pin. Receives the feedback voltage from an external resistive divider across the output. The internal voltage divider is disabled for adjustable version. (SGM6014-ADJ)
5 OUT		Output Voltage Pin. An internal resistive divider divides the output voltage down for comparison to the internal reference voltage. (SGM6014-3.3)
7, 8	SW	Switching Node Pin. Connect the output inductor to this pin.
9, 10	PGND	Power Ground.
Exposed Pad	GND	Analog Ground Exposed Pad. Must be connected to GND plane.

ELECTRICAL CHARACTERISTICS

(V_{IN} = 3.6V, T_A = -40°C to +85°C, unless otherwise noted.)

PARAMETER		SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Input Voltage Rar	nge		V _{IN}		2.5		5.5	V
Regulated Output Voltage		V _{OUT}		1.2		V _{IN} ⁽¹⁾	V	
	PWM I	Mode		V _{FB} = 0.58V	300 4		420	
Input DC	PFM	Adjustable Version	lo	V _{FB} = 0.62V		55	95	μA
Bias Current	Mode	Fixed Version	.4	V _{FB} = 0.62V		55	110	μ/ (
	Shutdo	own		V _{IN} = 5.5V, V _{EN} = 0V		0.01	2	
Feedback Input B	ias Curre	ent	I _{FB}	V _{FB} = 0.65V		0.001	1	μA
Regulated Feedback Voltage			V	V_{IN} = 2.5V to 5.5V, T_A = +25°C	0.587	0.6	0.616	v
		V _{FB}	V_{IN} = 2.5V to 5.5V, T_A = -40°C to +85°C	0.583	0.6	0.619	V	
Line Regulation			V_{IN} = 2.5V to 5.5V, I_{LOAD} = 350mA		0.1	0.6	%/V	
Load Regulation			I _{LOAD} = 200mA to 2000mA		0.07		%/A	
Output Voltage	Adjusta	able Version		V_{IN} = 2.5V to 5.5V, I_{LOAD} = 350mA	-3.5			%
Accuracy	Fixed Version			$V_{IN} = 2.5V$ to 5.5V, $I_{LOAD} = 350$ mA	-3.5		+5	%
Oscillator Frequer	псу		f _{osc}			1.4		MHz
Startup Time			ts	From Enable to Output Regulation		500		μs
Over-Temperature	e Shutdo	wn Threshold	t _{SD}			150		°C
Over-Temperature	e Shutdo	own Hysteresis	t _{HYS}			15		°C
Peak Switch Curr	ent		I _{PK}			2.7		А
R _{DS(ON)} of P-Chan	nel FET		6	V _{IN} = 3.6V		135		
R _{DS(ON)} of N-Channel FET		R _{DS(ON)}	V _{IN} = 3.6V		115		mΩ	
	Logic-l	High Voltage	$V_{\text{EN}_{\text{H}}}$	V _{EN} Rising	1.5			V
EN Threshold	Logic-l	_ow Voltage	$V_{\text{EN}_{L}}$	V _{EN} Falling			0.4	
Enable Leakage (Current		I _{EN}	V _{EN} = 0V or V _{IN}		0.01	1	μA

NOTE:

1. The maximum output voltage is 4.4V.



TYPICAL PERFORMANCE CHARACTERISTICS

 $T_A = +25^{\circ}C$, L = 2.2µH, CIN = COUT = 22µF, unless otherwise noted.



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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 $T_A = +25^{\circ}C$, L = 2.2µH, CIN = COUT = 22µF, unless otherwise noted.



TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 $T_A = +25^{\circ}C$, L = 2.2µH, CIN = COUT = 22µF, unless otherwise noted.



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2V/div

1V/div

500mA/div

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 T_A = +25°C, L = 2.2µH, CIN = COUT = 22µF, unless otherwise noted.





DETAILED DESCRIPTION

The SGM6014 is a step-down switching regulator optimized for battery-powered handheld applications. The regulator operates at typically 1.4MHz fixed switching frequency under heavy load condition to allow small external inductor and capacitors to be used for minimal printed-circuit board (PCB) area. At light load, the regulator can enter PFM mode to reduce the switching frequency, to minimize the switching loss and to maximize the battery life. The quiescent current under PFM mode with no loading is typically only 55µA. The supply current is typically only 0.01µA when the regulator is disabled.

PWM Control Scheme

The SGM6014 uses the peak-current-mode pulse-width modulation (PWM) control scheme for fast transient response and pulse-by-pulse current limiting. The current loop consists of the oscillator, the PWM comparator (COMP), current sensing circuit, and the slope compensation for the current loop stability. The current sensing circuit consists of the resistance of the P-Channel MOSFET when it is turned on and the current sense amplifier (CSA). The control reference for the current loops comes from the error amplifier (EAMP) of the voltage loop.

The PWM operation is initialized by the clock from the oscillator. The P-Channel MOSFET is turned on at the

beginning of a PWM cycle and the current in the P-Channel MOSFET starts ramping up. When the sum of the CSA output and the compensation slope reaches the control reference of the current loop, the PWM comparator COMP sends a signal to the PWM logic to turn off the P-Channel MOSFET and to turn on the N-Channel MOSFET. The N-MOSFET remains on till the end of the PWM cycle.

The output voltage is regulated by controlling the reference voltage to the current loop. The bandgap circuit outputs a 0.6V reference voltage to the voltage control loop. The feedback signal comes from the FB pin. The soft-start block only affects the operation during the start-up. The EAMP is a transconductance amplifier, which converts the voltage error signal to a current output. The voltage loop is internally compensated by an RC network.

PFM Mode

At light load the SGM6014 enters pulse frequency modulation (PFM) mode to minimize the switching loss by reducing the switching frequency.

The output voltage reduces gradually due to the load current discharging the output capacitor. When the output voltage drops to the nominal voltage, the regulator resumes normal PWM mode operation.



APPLICATION INFORMATION

Setting the Output Voltage

Figure 1 shows the basic application circuit with the SGM6014 adjustable output version. For applications requiring an adjustable output voltage, the SGM6014 adjustable version can be externally programmed. Resistors R1 and R2 in Figure 1 program the output voltage to be equal to or higher than 1.2V. To limit the bias current required for the external feedback resistor string while maintaining good noise immunity, the minimum suggested value for R2 is $41k\Omega$. Although a larger value will further reduce quiescent current, it will also increase the impedance of the feedback node, making it more sensitive to external noise and interference. Table 1 summarizes the resistor values for typical output voltages.

The external resistors set the output voltage according to the following equation:

$$V_{\text{OUT}} = 0.6V \times \left(1 + \frac{R1}{R2}\right) \qquad \qquad R1 = \left(\frac{V_{\text{OUT}}}{0.6V} - 1\right) \times R2$$

Table 1. Standard 1% Resistors Substituted forCalculated Values

V _{OUT} (V)	R1 (kΩ)	R2 (kΩ)
1.2	150	150
1.8	300	150
3.3	450	100

When the battery input voltage decreases near the value of the output voltage, the SGM6014 allows the main switch to remain on for more than one switching cycle and increases the duty cycle until it reaches 100%. The duty cycle D of a step-down converter is defined as:

$$D = t_{ON} \cdot f_{OSC} \cdot 100\% \approx \frac{V_{OUT}}{V_{IN}} \cdot 100\%$$

where t_{ON} is the main switch on-time and f_{OSC} is the oscillator frequency. The minimum on-time is typically 100ns; therefore, the minimum duty cycle is equal to 100 × 100ns × f_{OSC} (Hz).

Inductor Selection

For most designs, the SGM6014 operates with inductor values of 1μ H to 4.7μ H. Small value inductors are physically smaller but require faster switching, which results in some efficiency loss. The inductor value can be derived from the following equation:

$$L = \frac{V_{OUT} \cdot (V_{IN} - V_{OUT})}{V_{IN} \cdot \Delta I_{L} \cdot f_{OSC}}$$

where ΔI_L is inductor ripple current. Large value inductors lower ripple current and small value inductors result in high ripple current. Choose inductor ripple current approximately 30% of the maximum load current 2A, or ΔI_L = 600mA. For output voltages above 2.0V, when light-load efficiency is important, the minimum recommended inductor is 2.2µH.

Manufacturer's specifications list both the inductor DC current rating, which is a thermal limitation, and the peak current rating, which is determined by the saturation characteristics. The inductor should not show any appreciable saturation under normal load conditions. Some inductors may meet the peak and average current ratings yet result in excessive losses due to a high DCR.

Always consider the losses associated with the DCR and its effect on the total converter efficiency when selecting an inductor. For optimum voltage-positioning load transients, choose an inductor with DC series resistance in the $20m\Omega$ to $100m\Omega$ range. For higher efficiency at heavy loads (above 200mA), or best load regulation (but some transient overshoot), the resistance should be kept below $100m\Omega$. The DC current rating of the inductor should be at least equal to the maximum load current plus half the ripple current to prevent core saturation (2A + 600mA).

Slope Compensation

The SGM6014 step-down converter uses peak current mode control with slope compensation for stability when duty cycles are greater than 50%. The slope compensation is set to maintain stability with lower value inductors which provide better overall efficiency. The output inductor value must be selected so the inductor current down slope meets the internal slope compensation requirements.



APPLICATION INFORMATION (continued)

As an example, the value of the slope compensation is set to $1.5A/\mu s$ which is large enough to guarantee stability when using a $2.2\mu H$ inductor for all output voltage levels from 1.2V to 4.4V.

The worst case external current slope (m) using the 2.2 μ H inductor is when V_{OUT} = 4.4V. To keep the output voltage stable when the duty cycle is above 50%, the internal slope compensation (m_a) should be:

$$m_a \ge \frac{1}{2}m = \frac{1}{2} \times \frac{V_{OUT}}{L} = 1A/\mu s$$

Therefore, to guarantee current loop stability, the slope of the compensation ramp must be greater than one-half of the down slope of the current waveform. So the internal slope compensated value of $1.5A/\mu s$ will guarantee stability using a $2.2\mu H$ inductor value for all output voltages from 1.2V to 4.4V.

Input Capacitor Selection

The input capacitor reduces the surge current drawn from the input and switching noise from the device. The input capacitor impedance at the switching frequency should be less than the input source impedance to prevent high frequency switching current passing to the input. The calculated value varies with input voltage and is a maximum when V_{IN} is double the output voltage.

$$\begin{split} C_{IN} = & \frac{\frac{V_{OUT}}{V_{IN}} \cdot \left(1 - \frac{V_{OUT}}{V_{IN}}\right)}{\left(\frac{V_{PP}}{I_{LOAD}} - ESR\right) \cdot f_{OSC}} \\ C_{IN(MIN)} = & \frac{1}{\left(\frac{V_{PP}}{I_{LOAD}} - ESR\right) \cdot 4 \cdot f_{OSC}} \end{split}$$

A low ESR input capacitor sized for maximum RMS current must be used. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients. At least a 2.2μ F input capacitor is recommended. A 22μ F ceramic capacitor for most applications is sufficient. A large value may be used for improved input voltage filtering. The maximum input capacitor RMS current is:

$$\mathbf{I}_{\text{RMS}} = \mathbf{I}_{\text{LOAD}} \cdot \sqrt{\frac{V_{\text{out}}}{V_{\text{IN}}}} \cdot \left(1 - \frac{V_{\text{out}}}{V_{\text{IN}}}\right)$$

The input capacitor RMS ripple current varies with the input and output voltage and will always be less than or equal to half of the total DC load current:

$$I_{\text{RMS}(\text{MAX})} = \frac{1}{2} \cdot I_{\text{LOAD}}$$

A laboratory test set-up typically consists of two long wires running from the bench power supply to the evaluation board input voltage pins. The inductance of these wires, along with the low-ESR ceramic input capacitor, can create a high Q network that may affect converter performance. This problem often becomes apparent in the form of excessive ringing in the output voltage during load transients. Errors in the loop phase and gain measurements can also result.

Since the inductance of a short PCB trace feeding the input voltage is significantly lower than the power leads from the bench power supply, most applications do not exhibit this problem.

In applications where the input power source lead inductance cannot be reduced to a level that does not affect the converter performance, a high ESR tantalum or aluminum electrolytic capacitor should be placed in parallel with the low ESR, ESL bypass ceramic capacitor. This dampens the high Q network and stabilizes the system.

Output Capacitor Selection

The function of output capacitance is to store energy to attempt to maintain a constant voltage. The energy is stored in the capacitor's electric field due to the voltage applied.



APPLICATION INFORMATION (continued)

The value of output capacitance is generally selected to limit output voltage ripple to the level required by the specification. Since the ripple current in the output inductor is usually determined by L, V_{OUT} and V_{IN} , the series impedance of the capacitor primarily determines the output voltage ripple. The three elements of the capacitor that contribute to its impedance (and output voltage ripple) are equivalent series resistance (ESR), equivalent series inductance (ESL), and capacitance (C).

The output voltage droop due to a load transient is dominated by the capacitance of the ceramic output capacitor. During a step increase in load current, the ceramic output capacitor alone supplies the load current until the loop responds. Within three switching cycles, the loop responds and the inductor current increases to match the load current demand. The relationship of the output voltage droop during the three switching cycles to the output capacitance can be estimated by:

$$C_{\text{OUT}} = \frac{3 \cdot \Delta I_{\text{LOAD}}}{V_{\text{DROP}} \cdot f_{\text{OSC}}}$$

In many practical designs, to get the required ESR, a capacitor with much more capacitance than is needed must be selected. For both continuous and discontinuous inductor current mode operation, the ESR of the C_{OUT} needed to limit the ripple to ΔV_{OUT} , V peak-to-peak is:

$$\text{ESR} \leq \frac{\Delta V_{\text{OUT}}}{\Delta I_{\text{L}}}$$

Ripple current flowing through a capacitor's ESR causes power dissipation in the capacitor. This power dissipation causes a temperature increase internal to the capacitor. Excessive temperature can seriously shorten the expected life of a capacitor. Capacitors have ripple current ratings that are dependent on ambient temperature and should not be exceeded. The output capacitor ripple current is the inductor current, I_L , minus the output current. The RMS value of the ripple current flowing in the output capacitance (continuous inductor current mode operation) is given by:

$$I_{\text{RMS}} = \Delta I_{\text{L}} \cdot \frac{\sqrt{3}}{6} = \Delta I_{\text{L}} \cdot 0.289$$

ESL can be a problem by causing ringing in the low megahertz region but can be controlled by choosing low ESL capacitors, limiting lead length (PCB and capacitor), and replacing one large device with several smaller ones connected in parallel.

In conclusion, in order to meet the requirement of small output voltage ripple and regulation loop stability, ceramic capacitors with X5R or X7R dielectrics are recommended due to their low ESR and high ripple current ratings. The output ripple V_{OUT} is determined by:

$$\Delta V_{\text{OUT}} \leq \frac{V_{\text{OUT}} \cdot (V_{\text{IN}} - V_{\text{OUT}})}{V_{\text{IN}} \cdot L \cdot f_{\text{OSC}}} \cdot \left(\text{ESR} + \frac{1}{8 \cdot f_{\text{OSC}} \cdot C_{\text{OUT}}} \right)$$

A 22µF ceramic capacitor can satisfy most applications.

Thermal Calculations

There are three types of losses associated with the SGM6014 step-down converter: switching losses, conduction losses, and quiescent current losses. Conduction losses are associated with the $R_{DS(ON)}$ characteristics of the power output switching devices. Switching losses are dominated by the gate charge of the power output switching devices. At full load, assuming continuous conduction mode (CCM), a simplified form of the losses is given by:

$$P_{\text{TOTAL}} = \frac{I_{\text{LOAD}}^2 \cdot \left[R_{\text{DSON(HS)}} \cdot V_{\text{OUT}} + R_{\text{DSON(LS)}} \cdot \left(V_{\text{IN}} - V_{\text{OUT}} \right) \right]}{V_{\text{IN}}} + \left(t_{\text{SW}} \cdot F \cdot I_{\text{LOAD}} + I_{\text{Q}} \right) \cdot V_{\text{IN}}$$

 I_Q is the step-down converter quiescent current. The t_{SW} is used to estimate the full load step-down converter switching losses.

For the condition where the step-down converter is in dropout at 100% duty cycle, the total device dissipation reduces to:

$$\mathsf{P}_{\mathsf{TOTAL}} = \mathsf{I}_{\mathsf{LOAD}}^2 \cdot \mathsf{R}_{\mathsf{DSON(HS)}} + \mathsf{I}_{\mathsf{Q}} \cdot \mathsf{V}_{\mathsf{IN}}$$

Since $R_{DS(ON)}$, quiescent current, and switching losses all vary with input voltage, the total losses should be investigated over the complete input voltage range. Given the total losses, the maximum junction temperature can be derived from the θ_{JA} for the TDFN-3×3-10L package which is 45°C/W

$$T_{J(MAX)} = P_{TOTAL} \cdot \theta_{JA} + T_{AMB}$$



REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

SEPTEMBER 2017 - REV.A.2 to REV.A.3 Deleted SGM6014-1.2YTD10G and SGM6014-1.8YTD10G AUGUST 2015 - REV.A.1 to REV.A.2 Update exposed pad function .3 NOVEMBER 2013 - REV.A to REV.A.1 Add fixed output voltage versions Change ESD susceptibility .2 Change electrical characteristics .4 Changes from Original (JULY 2013) to REV.A

Changed from product preview to production dataAll
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PACKAGE OUTLINE DIMENSIONS

TDFN-3×3-10L



RECOMMENDED LAND PATTERN (Unit: mm)

Symbol		nsions meters	Dimensions In Inches		
	MIN	MAX	MIN	MAX	
A	0.700	0.700 0.800		0.031	
A1	0.000	0.050	0.000	0.002	
A2	0.203	3 REF	0.008 REF		
D	2.900	3.100	0.114	0.122	
D1	2.300	2.600	0.091	0.103	
E	2.900	3.100	0.114	0.122	
E1	1.500	1.800	0.059	0.071	
k	0.200) MIN	0.008	3 MIN	
b	0.180	0.300	0.007	0.012	
е	0.500) TYP	0.020	TYP	
L	0.300	0.500	0.012	0.020	



TAPE AND REEL INFORMATION

REEL DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TDFN-3×3-10L	13″	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton			
13″	386	280	370	5	DD0002		

